Technical Data ELX1147

Effective February 2022

BUSSMANN SERIES

2822HC

High current surface mount Brick fuse



Product features

- 7.7 x 6.0 x 4.3 mm surface mount package
- · High current Brick fuse
- · Current rating: 40 A to 125 A
- Voltage rating: Up to 80 Vdc
- · High interrupting rating
- · cURus recognized
- Single fuse solution for high current applications
- · Moisture sensitivity level: (MSL): 1

Applications

- · Servers and back planes
- Power distribution units (PDUs)
- Power supplies
- · Energy storage system
- Industrial automation tools
- · Robotic machinery
- · Telecom DC/DC power
- · Routers & switches

Agency information

cURus Recognition file number: E91958, Guide JFHR2 & JFHR8



Environmental compliance





Ordering part number

	<u> 282</u>	<u>2HC X</u>	<u>X -t</u>	<u>1 I</u>	H
Family code ———					
Ampere rating ———					
RoHS compliant ———					
Packaging code ———					

Packaging code suffix

TR (1000 parts on a 13" diameter tape and reel)



Electrical characteristics

Amp Rating	1.0 In minimum	2.5 In maximum
40 A ~ 125 A	4 hours	60 seconds

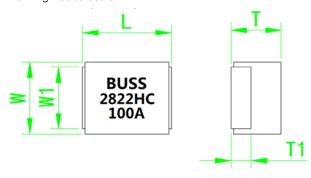
Product specifications

	Current rating	Voltage rating	Interrupting rating @ rated voltage ¹	Typical cold resistance ²	Typical voltage drop	
Part number	(A)	(Vdc)	(A)	(mΩ)	(mV)	Part marking
2822HC40-R	40	72*	1000 A @ 72 Vdc 1000 A @ 80 Vdc	1.10	75	BUSS 2822HC 40A
2822HC50-R	50	72*	1000 A @ 72 Vdc 1000 A @ 80 Vdc	0.87	75	BUSS 2822HC 50A
2822HC60-R	60	72*	1000 A @ 72 Vdc 1000 A @ 80 Vdc	0.78	100	BUSS 2822HC 60A
2822HC70-R	70	72*	1000 A @ 72 Vdc 500 A @ 80 Vdc	0.60	100	BUSS 2822HC 70A
2822HC80-R	80	72*	1000 A @ 72 Vdc 500 A @ 80 Vdc	0.58	100	BUSS 2822HC 80A
2822HC90-R	90	72*	1000 A @ 72 Vdc 500 A @ 80 Vdc	0.54	100	BUSS 2822HC 90A
2822HC100-R	100	72*	1000 A @ 72 Vdc 500 A @ 80 Vdc	0.45	100	BUSS 2822HC 100A
2822HC125-R	125	60	1000 A @ 60 Vdc	0.40	110	BUSS 2822HC 125A

^{1.} DC Interrupting rating (measured at designated voltage, time constant of less than 1 mlliseconds, battery source)

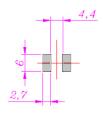
Dimensions- mm

Drawing not to scale

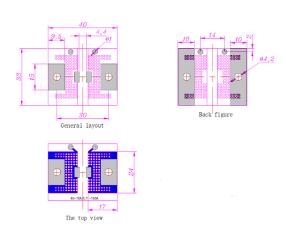


Amp rating	L	w	т	W1	T1
40 A - 90 A	7.6 ± 0.30	6.0 ± 0.30	4.2 ± 0.20	5.0 REF	1.6 REF
100 A - 125 A	7.7 ± 0.30	6.0 ± 0.30	4.3 ± 0.30	5.0 REF	1.6 REF

Recommended pad layout



Standard test board



Testing board: 1.6 mm FR4 PCB Copper thickness: 3 oz for 40 A – 70 A, 6 oz for above 70 A. Tin plated

^{2.} Typical cold resistance is measured at <10% of rated current in ambient temperature of +25 °C

^{*=} UL rated at 72 Vdc and 80 Vdc

General specifications

Operating temperature: -40 °C to +125 °C with proper derating factor applied

Soldering heat resistance: MIL-STD-202 method 210, Solder temperature +260 ±5 °C, solder immersion time 10±5 s

Solderability test: J-STD-002, method B1, Steam aging 1 hour, Solder temperature + 255 \pm 5 °C, solder immersion time 5 s

Thermal shock: MIL-STD-202 method 107, -40 °C/+125 °C. 1000 cycles, maximum transfer time 20 seconds, Dwell time 15 minutes. Air-Air

Humidity bias: MIL-STD-202 method 103, 1000 hours +85 °C/85% RH. at 10% of operating power.

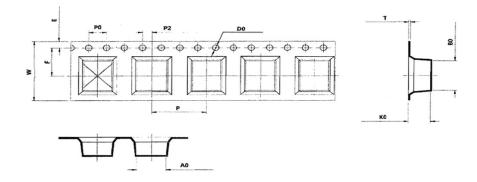
Vibration: MIL-STD-202F method 201, 2 hours each of 3 orientations. Test from 10-55 Hz for 1 minute

Mechanical shock: MIL-STD-202 method 213, Figure 1 of Method 213. Condition C 100 g 6 ms

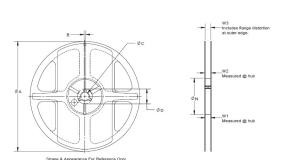
High temperature operating life: MIL-STD-202 method 108, Condition D steady state TA=+70 °C at 60% rated current.

Packaging information - mm

1000 parts per 13" diameter reel (EIA-481 compliant) Drawing not to scale



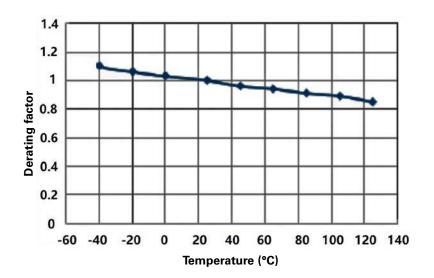
Reel dimension- mm



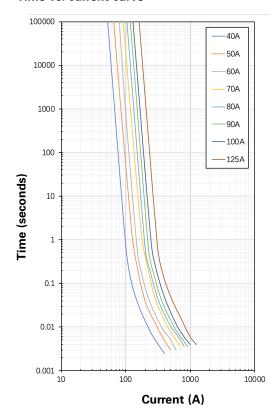
Dimension	millimeter
A	330
В	2.2
С	13.5
D	22
W1	16.5
W2	22.4 maximum

Dimension	millimeter
W	16.0
F	7.5
E	1.75
P0	4.0
P	12.0
P2	2.0
ØD0	1.50
ØD1	N/A
A0	6.3
B0	8.0
K0	4.7

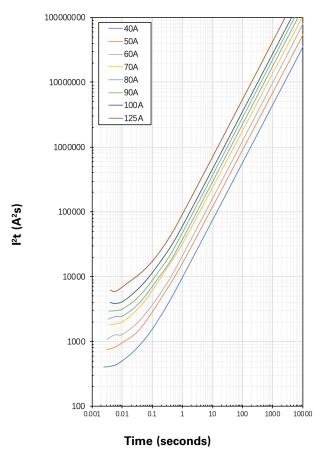
Temperature derating curve



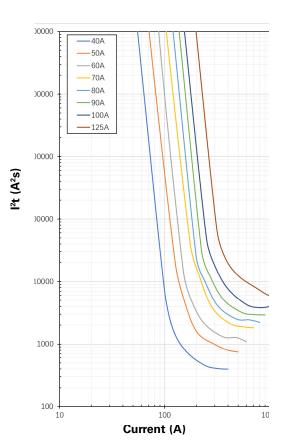
Time vs. current curve



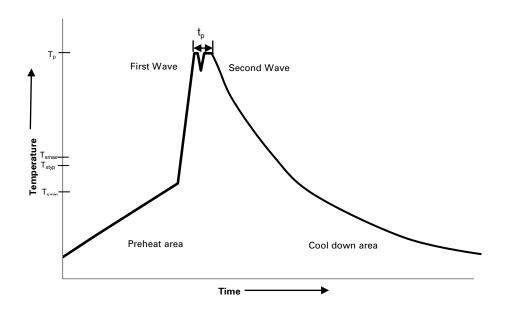
I²t vs. time curve



l²t vs. current



Wave solder profile



Reference

Profile feat	ure	Standard SnPb solder	Lead (Pb) free solder
Preheat	• Temperature min. (T _{smin})	100 °C	100 °C
	Temperature typ. (T _{styp})	120 °C	120 °C
	• Temperature max. (T _{smax})	130 °C	130 °C
	• Time (T _{smin} to T _{smax}) (t _s)	70 seconds	70 seconds
Δ preheat to	max Temperature	150 °C max.	150 °C max.
Peak tempera	iture (Tp)*	235 °C − 260 °C	250 °C − 260 °C
Time at peak	temperature (t _p)	6 seconds max 3 seconds max each wave	6 seconds max 3 seconds max each wave
Ramp-down r	ate	~ 2 K/s min ~3.5 K/s typ ~5 K/s max	~ 2 K/s min ~3.5 K/s typ ~5 K/s max
Time 25 °C to	25 °C	4 minutes	4 minutes

Manual solder

+350 °C (4-5 seconds by soldering iron), generally manual/hand soldering is not recommended.

Solder reflow profile

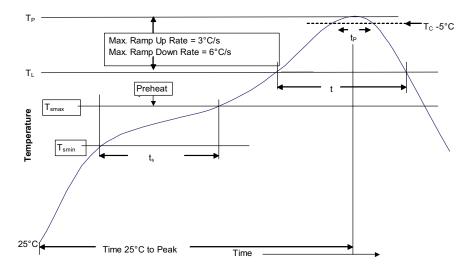


Table 1 - Standard SnPb solder (T_C)

Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak • Temperature min. (T _{smin})	100 °C	150 °C
Temperature max. (T _{Smax})	150 °C	200 °C
• Time (T _{Smin} to T _{Smax}) (t _S)	60-120 seconds	60-120 seconds
Ramp up rate T_L to T_p	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (TL) Time (t _L) maintained above T _L	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time (t _p)* within 5 °C of the specified classification temperature (T _c)	20 seconds*	30 seconds*
Ramp-down rate (T _p to T _L)	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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